

NEW



0.3mm Pitch Connector for FPC

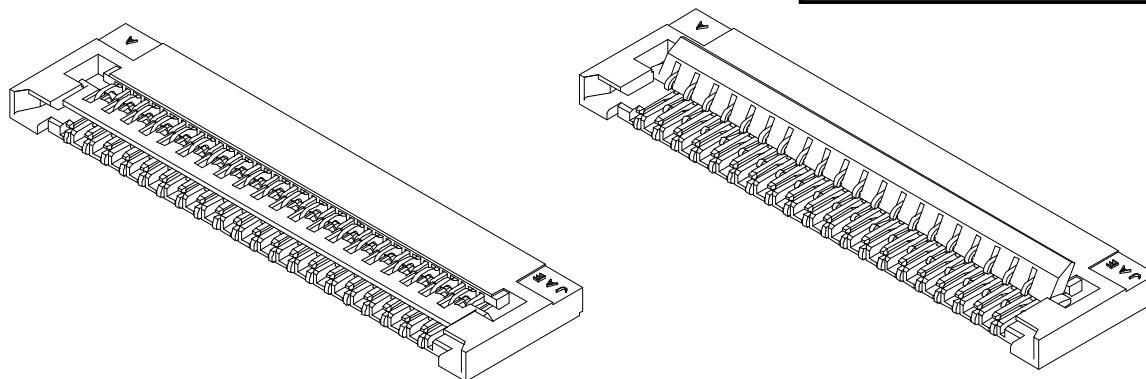
CONNECTOR

MB-0146-2

July 2006

FF02S Series

RoHS Compliant



Outline

The FF02S Series is a 0.3mm pitch low-profiled connector used for FPC connection with drop impact and vibration resistance responding to slim, compact information communication-related devices including mobile phones, LCDs and PDAs.

Features

- * Compact and low-profiled connector, 0.9mm height and 3.8mm depth.
- * Built-in actuator cam with proprietary structure that holds FPC at all contact points and enables complete mating even for multi-contacts.
- * Pb-free (solder migration prevented by nickel barrier in contact)

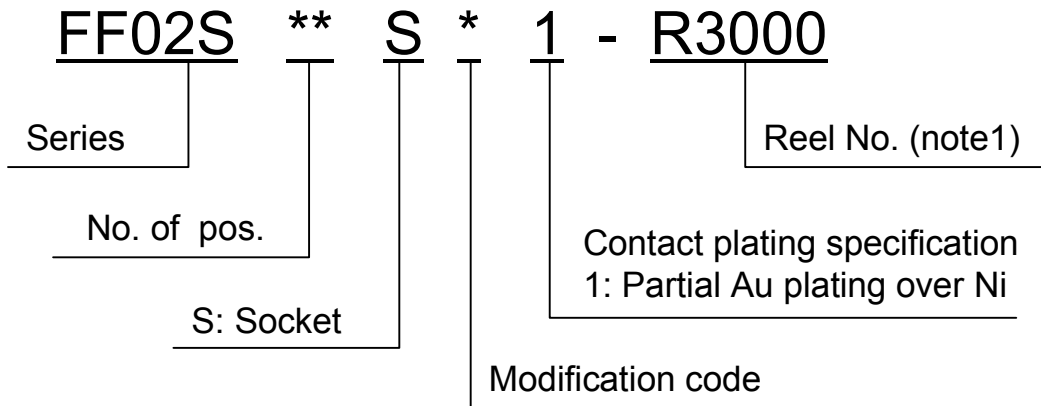
General Specifications

- | | |
|--|---|
| <ul style="list-style-type: none"> ■ No. of contacts : 25, 31, 33, 40, 45, 55,
(15, 17, 27, 29, 35, 60, 65)
Numbers shown in parentheses are planned ■ Rated current:
AC, DC 0.35A per pin, each ■ Rated voltage: AC, DC 50V ■ Operating temperature:
-40 Deg. C to +85 Deg. C | <ul style="list-style-type: none"> ■ Contact resistance:
40m ohm max. ■ Insulation resistance:
100M ohm min. ■ Dielectric withstanding voltage:
AC250Vr.m.s per minute ■ Applicable FPC thickness:
t=0.12 +0.03,-0.03 |
|--|---|

Materials and Finishes

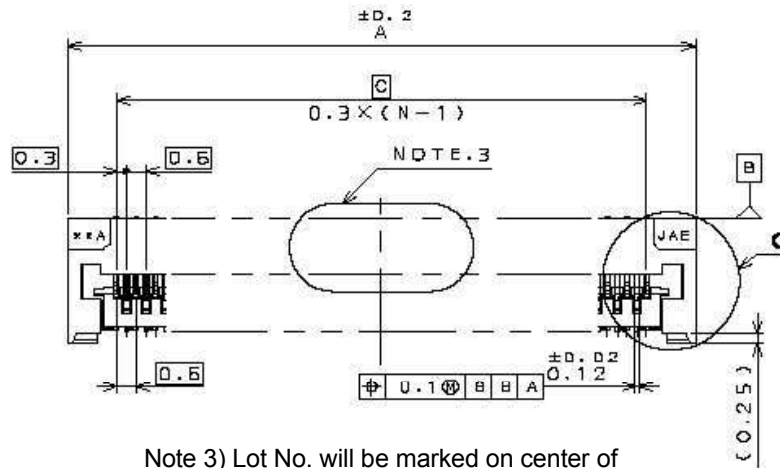
Components	Materials & Finishes
Actuator	PPS (UL94V-0, Color: Black)
Base insulator	LCP (UL94V-0, Color: White)
Contact	Copper Alloy/ Partial Au Plating over Ni Contact area: 0.1um Au min. Terminal area: 0.03um Au min.

Ordering Information

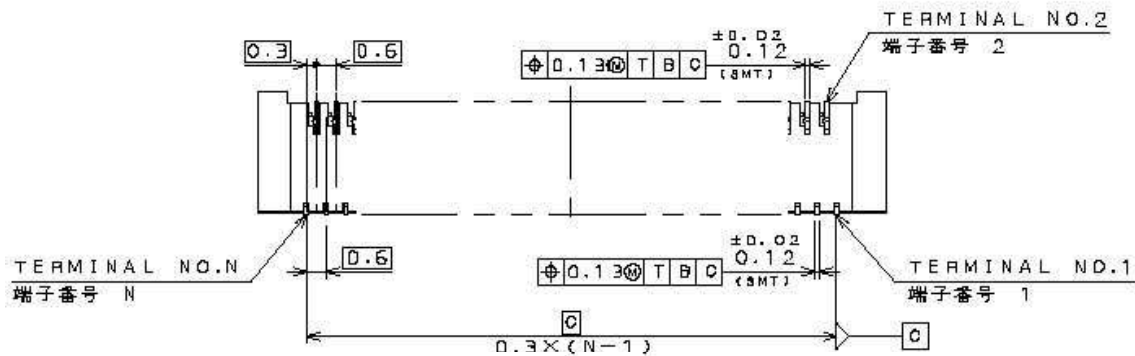
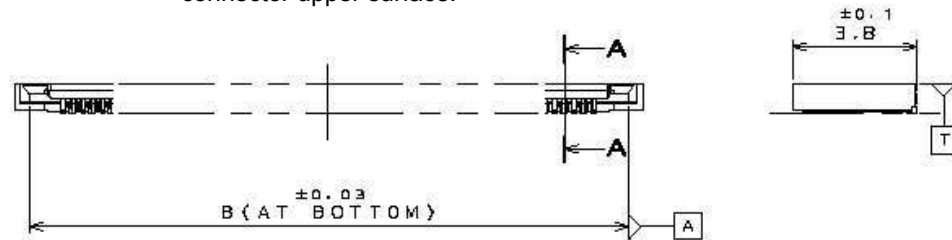


Note1) An embossed tape reel contains 3000 pieces.
Please contact us for embossed tape specifications.

-Number of pos. (Odd)

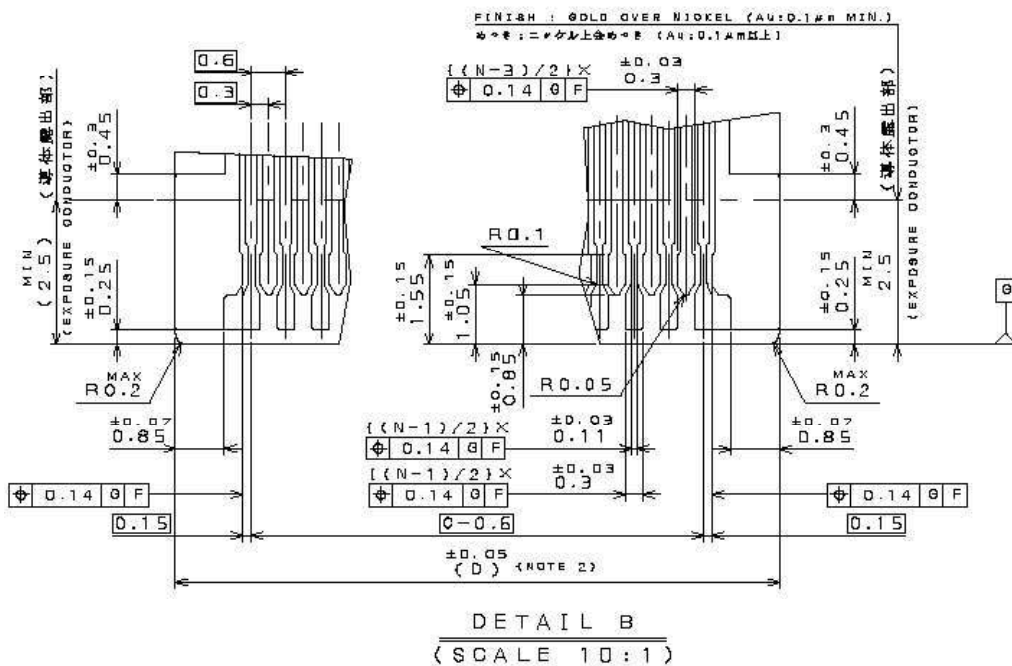
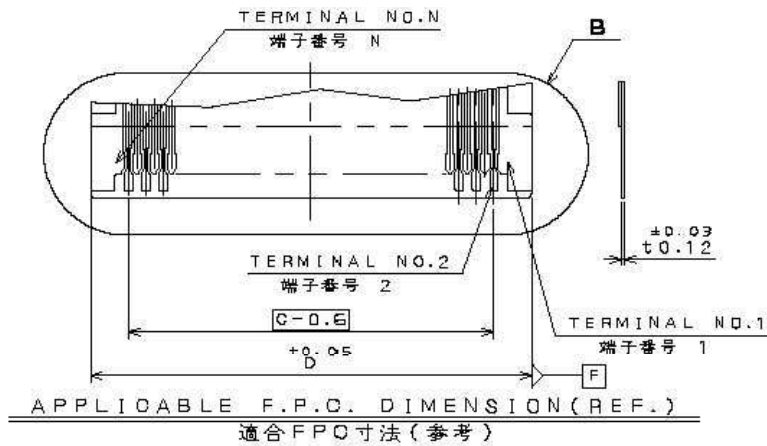
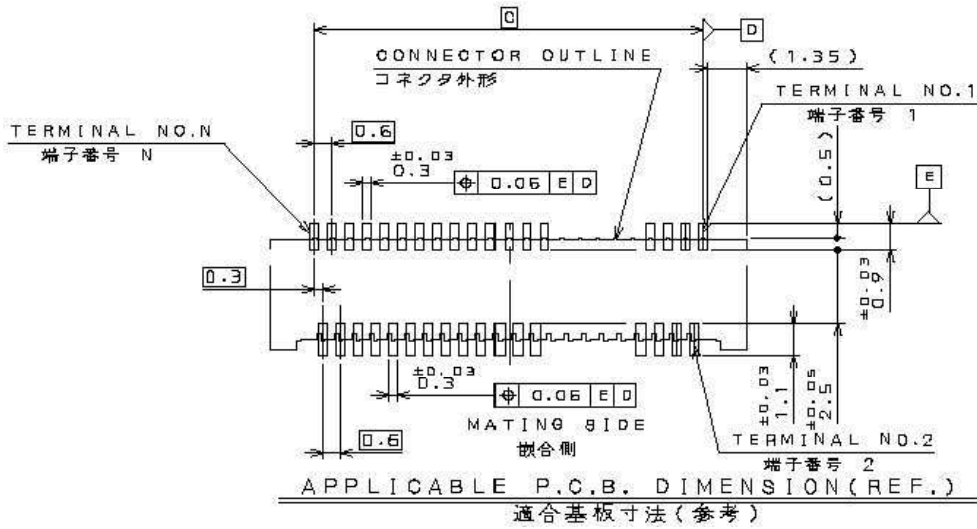


Note 3) Lot No. will be marked on center of connector upper surface.



Product No.	A	B	C	D
FF02S65SV1	22.20	21.31	19.20	21.24
FF02S55SV1	19.20	18.31	16.20	18.24
FF02S45SV1	16.20	15.31	13.20	15.24
FF02S35SV1	13.20	12.31	10.20	12.24
FF02S33SV1	12.60	11.71	9.60	11.64
FF02S31SV1	12.00	11.11	9.00	11.04
FF02S29SV1	11.40	10.51	8.40	10.44
FF02S27SV1	10.80	9.91	7.80	9.84
FF02S25SV1	10.20	9.31	7.20	9.24
FF02S17SV1	7.80	6.91	4.80	6.84
FF02S15SV1	7.20	6.31	4.20	6.24

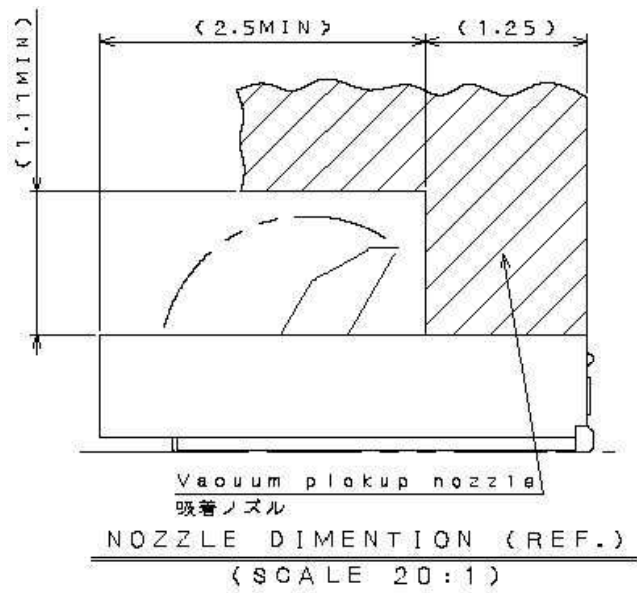
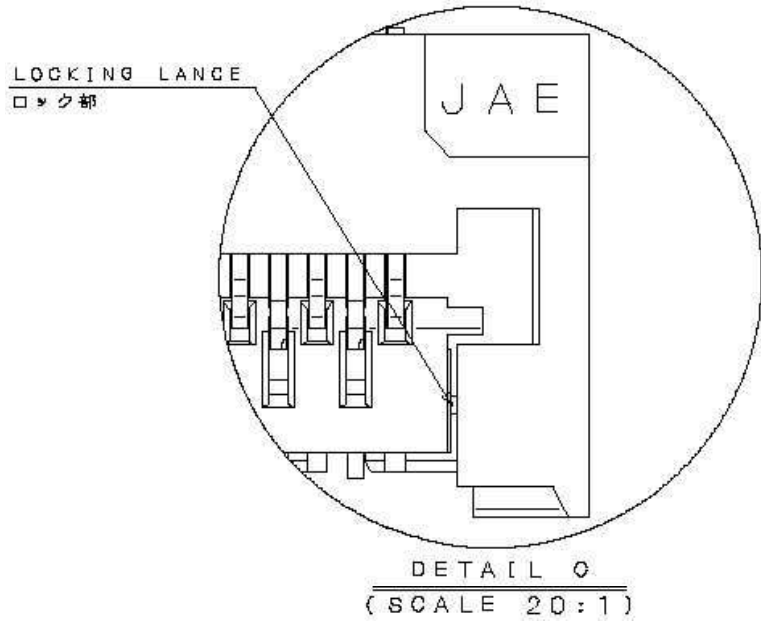
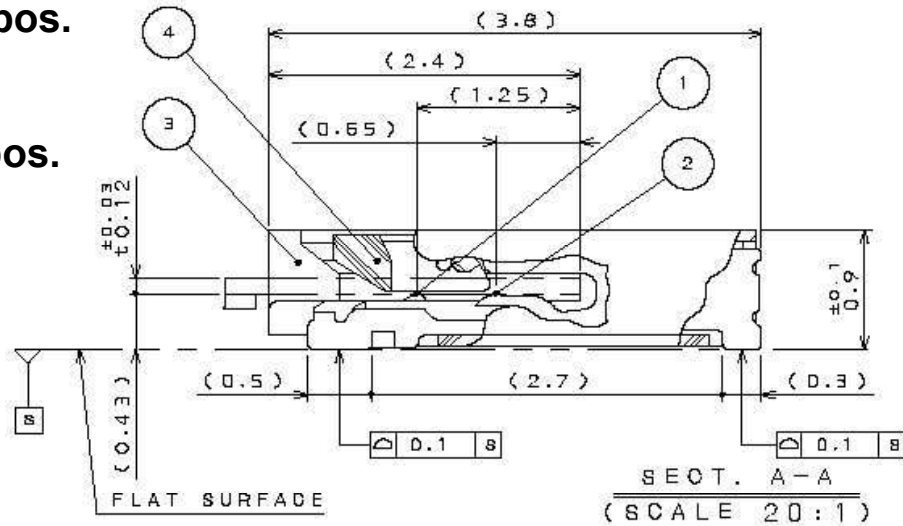
-Number of pos. (Odd)



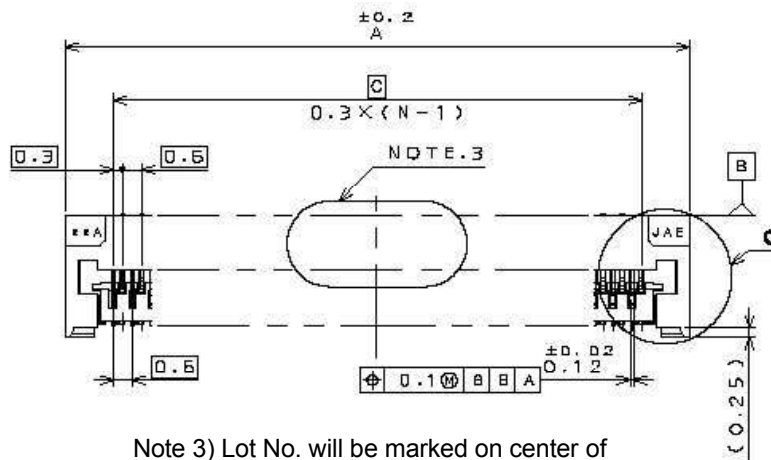
Note 2) To improve reliability of pitch direction positioning accuracy +0.05 -0.01 is recommended for dimension D.

-Number of pos.
(Odd)

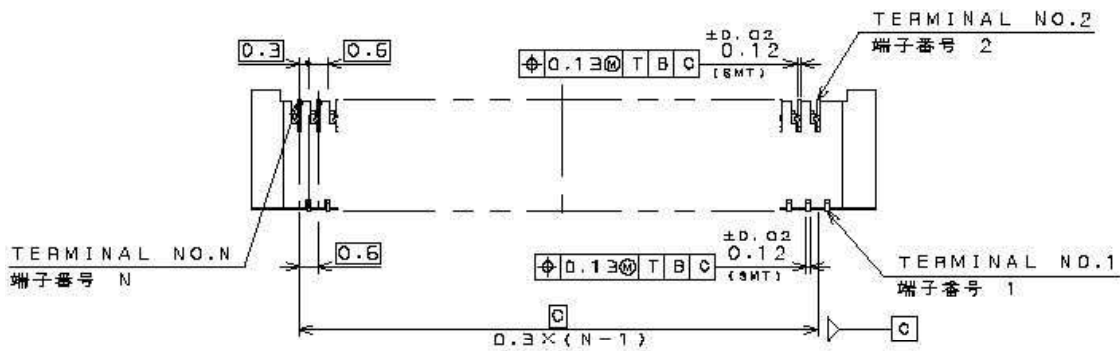
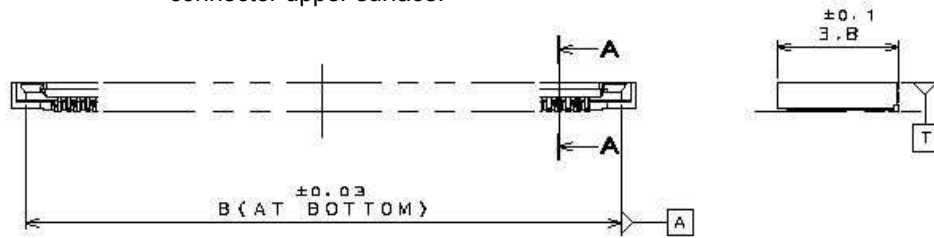
-Number of pos.
(Even)



-Number of pos. (Even)

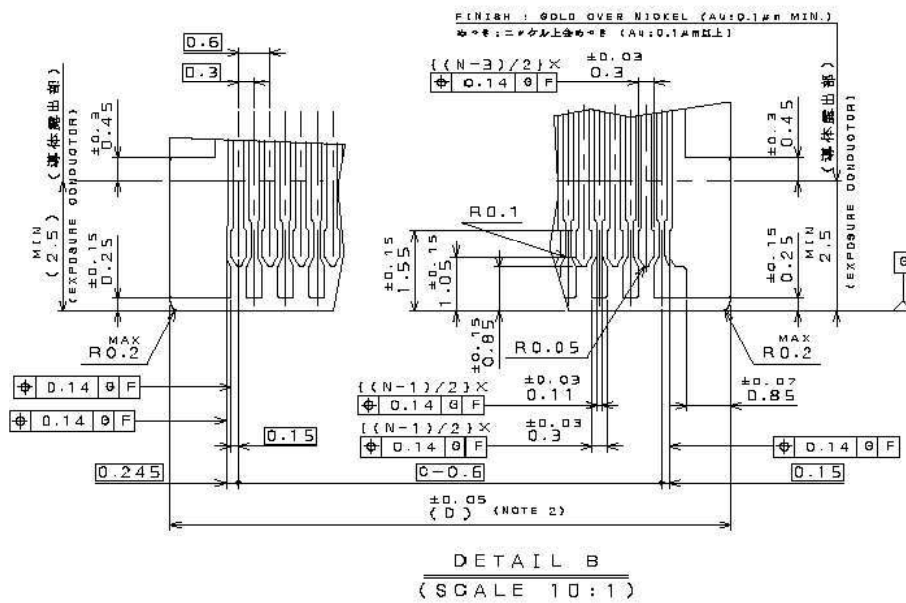
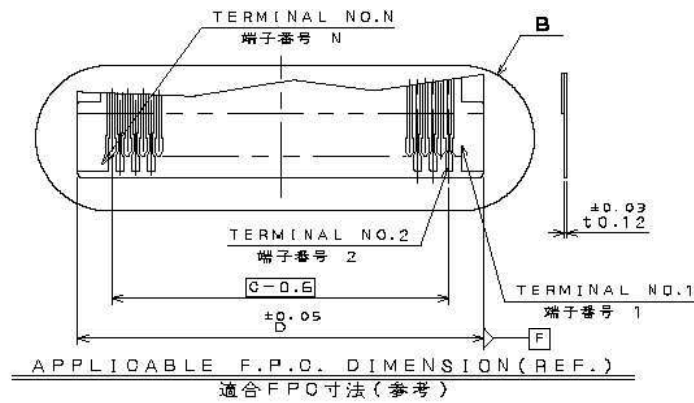
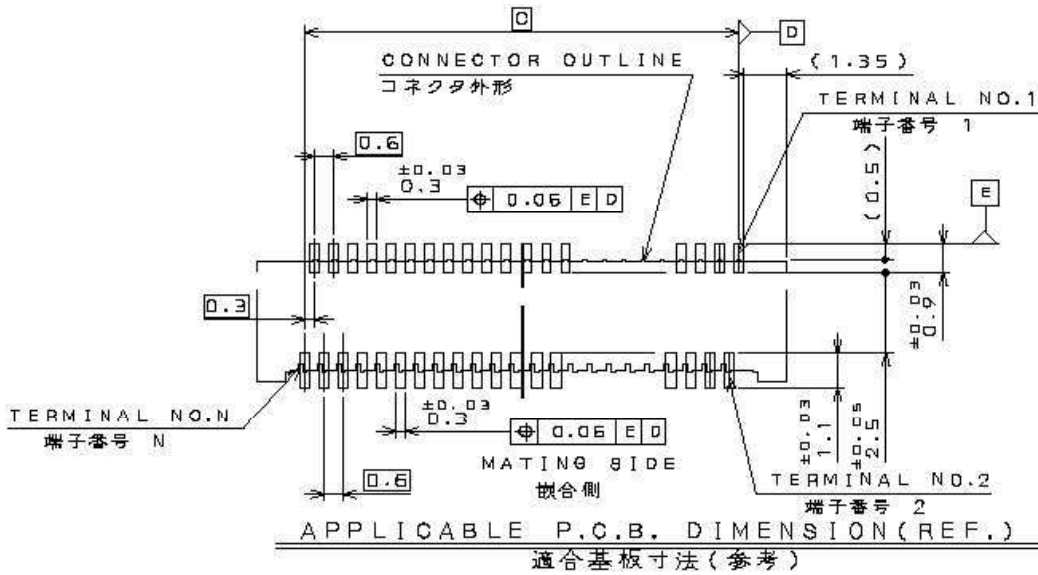


Note 3) Lot No. will be marked on center of connector upper surface.



Product No.	A	B	C	D
FF02S60SV1	20.70	19.81	17.70	19.74
FF02S50SV1	17.70	16.81	14.70	16.74
FF02S40SV1	14.70	13.81	11.70	13.74

-Number of pos. (Even)



Note 2) To improve reliability of pitch direction positioning accuracy +0.05 -0.01 is recommended for dimension D.

FPC configuration (Recommended)

Composition		Recommended
Gold Plating	Electrolysis Plating	0.1um min.
Nickel Plating	Electrolysis Plating	Soft type (If available)
Copper	Rolled Material	Nominal 18um max.
Adhesive	Thermosetting Adhesive	None (Recommended)
Base Film	Polyimide	25um
Adhesive	Thermosetting Adhesive	30um max.
Reinforce Plante	Polyimide	-

Specification	Document No.
Drawing	SJ104079 (odd number) SJ104400 (even number)
Specification Table	JACS-10293
Operating Manual	JAHL-10293

(Note) Be sure to request specifications.

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Notice: Products shown in this leaflet are made for the applications listed below. However, if the above-mentioned products are to be used in aerospace devices, marine cable-connection devices, atomic power control systems, medical equipment for life-support systems, or any other specific application requiring extremely high reliability, please contact JAE for further information.
Recommended applications: Computers, Office machines, Measuring devices, Telecommunication devices (Terminals, Mobile devices), AV devices, Household applications, FA devices, etc.